

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	Park <i>et al.</i>
Appl. No.	:	10/500,494
Filed	:	December 27, 2004
For	:	METHOD OF FORMING COPPER INTERCONNECTIONS FOR SEMICONDUCTOR INTEGRATED CIRCUITS ON A SUBSTRATE
Examiner	:	Thanh V. Pham
Group Art Unit	:	2823

RESPONSE TO FINAL OFFICE ACTION

*OK to enter  
w/p  
01/18/2007*

**Mail Stop AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Final Office Action mailed on November 13, 2006, please amend the above-captioned application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 4 of this paper.